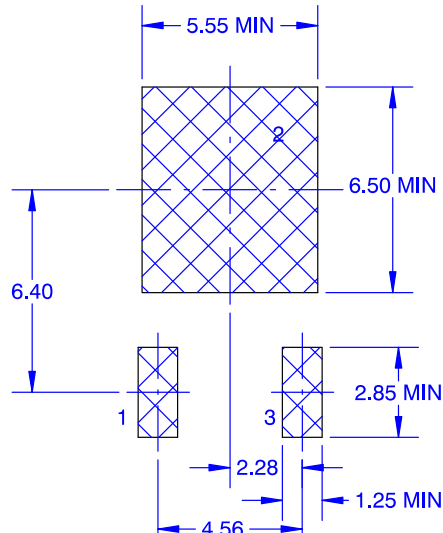
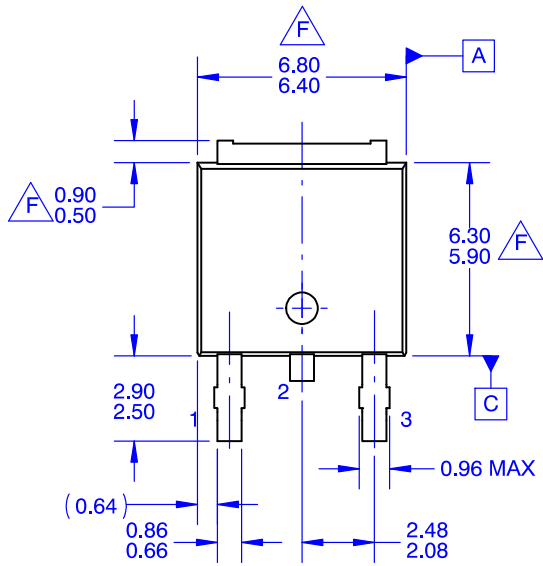


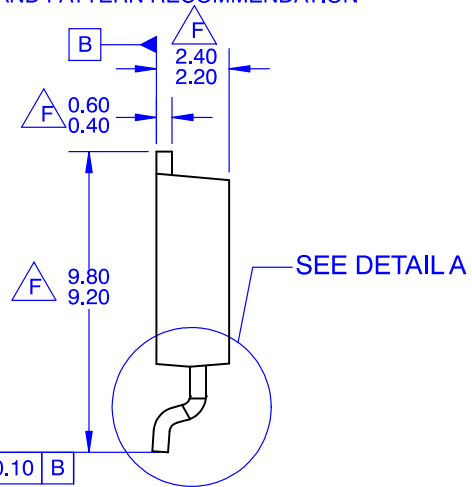
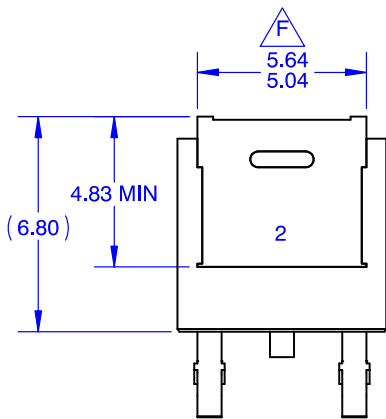
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

DPAK3
CASE 369AK
ISSUE O

DATE 30 SEP 2016

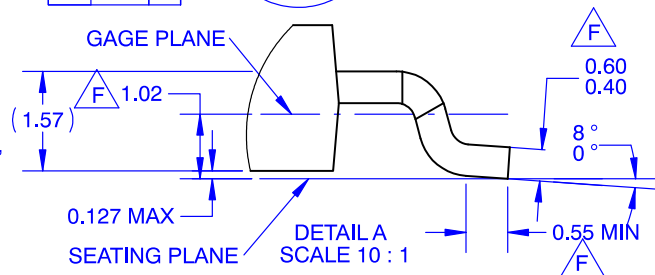


LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

- A) NOT COMPLIANT TO JEDEC TO-252 VARIATION AB
- B) ALL DIMENSION ARE IN MILLIMETER
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D) LAND PATTERN PER IPC7351A STANDARD TO228P991X239-3N
- E) DOES NOT COMPLY TO JEDEC STANDARD VALUE.



DOCUMENT NUMBER:	98AON13809G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	DPAK3	PAGE 1 OF 2

